

## **ZBC-3 (ZBC-IMX104)**

H.264 high profile 720p at 30fps





- TI DM368 SoC inside
- SONY Mega pixel progressive CMOS

**ZBC-3 - IMX104 1.3M pixel** 

ZBC-2 - IMX036 3M pixel

- 18x optical zoom
- Advance / Adaptive noise reduction

ZBC-3 - 2D+3D noise filter

ZBC-2 - 2D noise filter

More than 100dB WDR



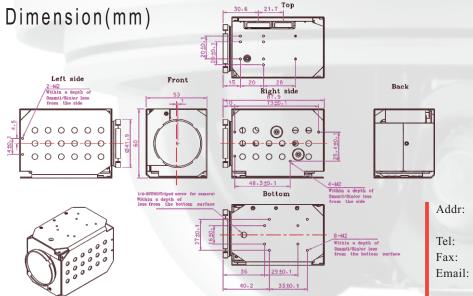




## Specifications.

ZBC-IMX036(ZBC-2)	ZBC-IMX104(ZBC-3)
Platform:TI TMS320DM368(432MHz)	Platform :TI TMS320DM368(432MHz)
Sensor: Sony 3M CMOS sensor(IMX036)	<ul> <li>Sensor: Sony 1.3M CMOS sensor(IMX104)</li> </ul>
Highest resolution: 2048 × 1536	● Highest resolution: 1280 × 1024
	Sensor
Active array size : 2048x1536	<ul> <li>Active array size : 1280x1024</li> </ul>
Temperature range:	Temperature range:
Operating: -10°C to 60°C	Operating: -10°C to 60°C
Stable image: -10°C to 60°C	Stable image: -10°C to 60°C
Pixel Size : 2.5um x 2.5um	• Pixel Size : 3.75um x 3.75um
Package dimensions: 15mm x 14.5mm	Package dimensions: 12.8mm x 11.6mm  Lens
<ul> <li>Lens: Tamron DF003N01300</li> </ul>	LGIIS
• Focal length : Fw : 4.70±0.235mm / Ft : 84.6±4.23r	mm
Zoom Ratio: 18X	
• Max Aperture : Fw :1.6 / Ft : 2.8	
<ul> <li>Angle of View: Fw: 42.1~67.3 / Ft: 2.4~4.0</li> </ul>	
<ul> <li>Focus Range: 1m~INF</li> </ul>	
Back focus with IR-CUT	
	Min illumination
Color: 0.2 lux @ F1.4	• Color: 0.1 lux @ F1.4
B/W: 0.01 lux @ F1.4	• B/W : 0.01 lux @ F1.4
More than 100dB WDR	<ul> <li>More than 100dB WDR</li> </ul>
2D Noise Filter	2D/3D Noise Filter
• Focus : Manual focus, Auto Focus, Continuous Focus(3M~	Video
<ul> <li>System: NTSC/PAL</li> <li>Configuration: WDR, Brightness, Contrast, Frame rate pri Motion Detection: 3 levels</li> <li>Compression: H.264/MPEG4/MIPEG (Triple streaming)</li> </ul>	iority, Quality priority, AWB , Sharpness , Saturation , Denoise, EV compensation
Compression: 11.20-//WI EG-//WIJI EG (Triple sucanning)	External Interface
<ul> <li>Interface: Ethernet (RJ-45 wired, 10/100 base-TX), Support</li> </ul>	t Protocols : TCP/IP,DHCP,HTTP,UDP,UPnP,FTP,SMTP,RTP
<ul> <li>Serial port: RS-485, Support Pelco-D, Pelco-P</li> </ul>	
Digital output: BT.1120	
	Software
MontaVista Linux	
Web-broswer - Microsoft IE 6.0 or above	
	Audio
• built-in microphone : μ law , 8KHz sample rate	
Reset : factory default	Others
LED indicator : Power / Network	Ouleis
Firmware update: upgrade with SD/HTTP	
Power requirement : DC 12V	
Operation Temperature : 0°C~60°C	
• Dimension : 60(W) × 53(H) × 87.9(L) mm	
	Resolution
H.264 3MP 20fps	H.264 1280x720 30fps
MPEG4 3MP 20fps	MPEG4 1280x720 30fps
JPEG 3MP 20fps	JPEG 1280x720 30fps
H.264 1080P 30fps	H.264(1280x720 30fps)/JPEG(VGA)/G.711 dual streaming
MPEG4 1080P 30fps	H.264(D1)*2 dual streaming
JPEG 1080P 30fps	MPEG4(1280x720 30fps)/MPEG4(CIF))/G.711 dual streaming
H.264 SXGA 30fps	MPEG4(1280x720 30fps)/JPEG(VGA))/G.711 dual streaming
MPEG4 SXGA 30fps	
H.264(720P)/H.264(CIF)/G.711 dual streaming	
H.264(720P)/JPEG(VGA)/G.711 dual streaming	
H.264(D1)*2 dual streaming	
MPEG4(720P)/MPEG4(CIF)/G.711 dual streaming MPEG4(720P)/JPEG(VGA)/G.711 dual streaming	
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40PIN interface		
No.	Name	
1	DC12V	
2	DC12V	
3	DC12V	
4	DC12V	
5	DC12V	
6	AGND (1)	
7	TD+ (ETHERNET: CHIP SIDE)	
8	TD- (ETHERNET: CHIP SIDE)	
9	TRCT	
10	RD+ (ETHERNET: CHIP SIDE)	
11	RD- (ETHERNET: CHIP SIDE)	
12	GND	
13	USB_VBUS (USB)	
14	USB_DP (USB)	
15	USB_DM (USB)	
16	GND	
17	RS485_D-	
18	RS485_D+	
19	GND	
20	MIC_IN	
21	AUDIO_OUT	
22	TV_OUT	
23	A_GND (2)	
24	GND	
25	SD_DATA0	
26	SD_DATA1	
27	SD_DATA2	
28	SD_DATA3	
29	SD_CMD	
30	SD_CLK	
31	BOOT_SEL	
32	IRDA_DET_IN	
33	MODE	
34	ALARM RESET	
35	ALARM IN	
36	ALARM OUT	
37	KEY1/LDE1	
38	KEY2/LDE2	
39	KEY3/LDE3	
40	VCC3.3VD	
(1) AGND: For Ethernet GND		
(2) A_	(2) A_GND: For MIC, AUDIO and TV OUT.	





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H.264(720P)/JPEG(VGA)/H.264(CIF)/G.711 triple streaming MPEG4(720P)/JPEG(VGA)/MPEG4(CIF)/G.711 triple streaming

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